

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TANAKA, et al.

Serial No.: 10/537,959

Filed: June 7, 2005

For: Thermoplastic Polyimide Resin  
Film, Multilayer Body and  
Method for Manufacturing  
Printed Wiring Board Composed  
of Same

Art Unit: 1796

Conf. No.: 1391

Examiner: Gregory Listvoyb

**RESPONSE TO RESTRICTION REQUIREMENT**

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Restriction Requirement dated August 4, 2008, Applicants elect for prosecution Group III, claims 12-15, without traverse.

If there are any fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-1314.

Respectfully submitted,

HOGAN & HARTSON L.L.P.

Date: November 11, 2008

By: 

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